

**NOTICE OF CONVENING A MEETING OF BONDHOLDERS OF SERIES
T BONDS
OF THE COMPANY "WORK SERVICE "S.A.
WITH ITS REGISTERED OFFICE IN WROCLAW**

Wroclaw, 8 November 2018

1. CONVENING A MEETING OF BONDHOLDERS

1.1 "Work Service" S.A. with its registered office in Wroclaw, ul. Gwiaździsta 66, 53-413 Wroclaw, entered into the Register of Entrepreneurs of the National Court Register under the number KRS 0000083941, whose registration files are kept by the District Court for Wroclaw-Fabryczna in Wroclaw, 6th Commercial Division of the National Court Register, holding REGON number 932629535 and NIP number 8971655469, with a share capital of PLN 6.509.482.30 (the "Issuer"), acting pursuant to Article 50(1)(3) and Article 51 (1-3) of the Bond Act of 15 January 2015 (the "**Bond Act**"), hereby convenes on its own initiative a meeting of bondholders of series T bonds (the "**Meeting of Bondholders**").

1.2 The Meeting of Bondholders will be held on 29 November 2018 at 10:00 in the Issuer's office at Puławska 2, 02-566 Warszawa (Warsaw).

2. SUBJECT MATTER AND AGENDA OF THE MEETING OF BONDHOLDERS

2.1 The subject matter of the Meeting of Bondholders will be an amendment to the terms and conditions of issue of Series T bonds issued by the Issuer on 4 December 2015. ("**Issue Conditions**").

2.2 The following agenda shall be established for the Meeting of Bondholders:

2.2.1 opening of the Meeting of Bondholders;

2.2.2 election of the Chairman of the Meeting of Bondholders;

2.2.3 making an attendance list;

2.2.4 stating the proper convening of the Meeting of Bondholders and capacity to adopt Resolutions.

2.2.5 giving the floor to participants of the Meeting of Bondholders on the resolutions adopted;

2.2.6 approval of the Meeting of Bondholders agenda;

2.2.7 voting by the Meeting of Bondholders on the adoption of resolution or resolutions on the amendment of the Issue Conditions, including in particular the amendment of the definition of the Redemption Date;

2.2.8 closing of the Meeting of Bondholders;

- 23 The Bondholder has the right to demand a copy of documents concerning matters included in the agenda. Copies of relevant documents should be issued no later than 7 days before the date of the Meeting of Bondholders.

3. PARTICIPATION IN THE MEETING OF BONDHOLDERS

- 3.1 The Meeting of Bondholders may be attended by the bondholders who, in accordance with point 3.2 below, submitted to the Issuer's office at ul. Puławska 2, 02-566 Warsaw certificate referred to in Art. 55 (1) of the Bond Act. Bonds held by entities belonging to the Issuer's capital group within the meaning of Art. 3(1)(44) of the Accounting Act of 29 September 1994 do not entitle to participate in the Meeting of Bondholders.
- 3.2 The certificate referred to above should be submitted by a bondholder at least 7 days before the date of the Meeting of Bondholders and may not be collected before its completion.
- 3.3 For at least 3 business days prior to the opening of the Meeting of Bondholders, the Issuer shall make available at its registered office the list of bondholders entitled to participate in the Meeting of Bondholders. The Bondholder has the right to review the list and demand a copy of the list against reimbursement of the costs of its preparation or sending the list free of charge by e-mail to the address indicated by the Bondholder.
- 3.4 Bondholder may participate in the Meeting of Bondholders and execute the voting right personally or by attorney. Granting and revoking a power of attorney must be made in writing otherwise it will be null and void.
- 3.5 A bondholder's attorney may not be a member of the Issuer's governing bodies, an employee of the Issuer, a member of the governing bodies of an entity exercising control over the Issuer or an employee of such an entity. The provisions on the exercise of voting rights by attorney shall apply accordingly to the exercise of voting rights by another representative.
- 3.6 Detailed rules concerning the conduct of and participation in the Meeting of Bondholders are set forth in the Terms of Issue and the Bond Act.